

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (previously presented): An optical assembly, comprising:

a package including an optoelectronic component;

an alignment feature mounted to a surface of the package; and

a sleeve defining only one bore with an inner surface having a constant inner diameter for receiving and contacting outer surfaces of the alignment feature and a ferrule of a fiber optic connector when the alignment feature and the ferrule are inserted into the bore at opposite ends of the bore so they can be aligned relative to each other.

Claim 2 (previously presented): An optical assembly, comprising:

a package including an optoelectronic component;

an alignment feature mounted to a surface of the package;

a sleeve defining only one bore with an inner surface having a constant inner diameter;

a fiber optic connector comprising a ferrule;

wherein the alignment feature and the ferrule are inserted into the bore at opposite ends of the bore so they can be aligned relative to each other.

Claim 3 (original): The assembly of claim 1, wherein the alignment feature comprises a cylindrical post having a hole allowing a light emitted by the package to pass through.

Claim 4 (original): The assembly of claim 1, wherein the alignment feature comprises a solid post comprising a transmissive material allowing a light emitted by the package to pass through.

Claim 5 (previously presented): The assembly of claim 1, wherein the alignment feature comprises a solid partial sphere comprising a transmissive material allowing a light emitted by the package to pass through, the outer surface of the solid partial sphere contacting the inner surface of the single bore of the sleeve.

Claim 6 (canceled).

Claim 7 (previously presented): The assembly of claim 2, wherein the fiber optic connector is selected from the group consisting of an LC connector, an ST connector, an SC connector, and an FC connector.

Claim 8 (original): The assembly of claim 1, wherein the package is selected from a group consisting of an optoelectronic chip enclosure (OECE) and a TO can.

Claim 9 (original): The assembly of claim 1, wherein the optoelectronic component is a laser.